FIG. 1

START

S101

FORM MAGNET BODY THROUGH SINTERING METHOD OR THE LIKE

S102

FORM FIRST PROTECTIVE FILM THROUGH ELECTROPLATING USED FIRST PLATING BATH

NICKEL SOURCE (0.3-0.7mol/1 ON A NICKEL ATOM BASIS) CONDUCTIVE SALT

pH STABILIZER

CONDUCTIVITY 80mS/cm OR OVER

S103

FORM SECOND PROTECTIVE FILM THROUGH ELECTROPLATING USED SECOND PLATING BATH

NICKEL SOURCE

CONDUCTIVE SALT

pH STABILIZER

ORGANIC SULFUR COMPOUND

CONDUCTIVITY 80mS/cm OR OVER

END